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AMENDMENT

Please amend the application as indicated hereafter.

To the Claims:

- 1. (original) A flip-chip gold bump structure formed on a wafer, comprising:
- at least one gold bump;
- a nickel layer on the gold bump; and
- a copper layer on the nickel layer.
- 2. (original) The flip-chip gold bump structure of claim 1, wherein the nickel layer has a thickness about from 0.1 μ m to about 20 μ m.
- 3. (original) The flip-chip gold bump structure of claim 1, wherein the copper layer has a thickness about from 0.1 μm to about 10 μm .
- 4. (original) The flip-chip gold bump structure of claim 1, wherein the gold bump has a height about from 3 μm to about 150 μm .
- 5. (original) A flip-chip package structure adapted to connect a chip and a chip substrate, comprising:
 - at least one gold bump on the chip;
 - a nickel layer on the gold bump; and
- a solder containing copper on the nickel layer for connecting the chip and the chip substrate.

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- 6. (original) The flip-chip package structure of claim 5, wherein the solder containing copper includes a solder alloy.
- 7. (original) The flip-chip package structure of claim 6, wherein copper in the solder alloy is from about 0.7 wt.% to about 3.0 wt.%.
- 8. (original) The flip-chip package structure of claim 5, wherein the nickel layer has a thickness about from 0.1 μm to about 20 μm .
- 9. (original) The flip-chip package structure of claim 5, wherein the gold bump has a height about from 3 μm to about 150 μm .
 - 10. (cancelled)
 - 11. (cancelled)
 - 12. (cancelled)
 - 13. (cancelled)
 - 14. (cancelled)
 - 15. (cancelled)
 - 16. (cancelled)
 - 17. (cancelled)
 - 18. (cancelled)
 - 19. (cancelled)
 - 20. (cancelled)
 - 21. (cancelled)
 - 22. (cancelled)

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CONCLUSION

Pursuant to Examiner's instruction, a complete listing of all the claims is now presented. If the Examiner believes that a conference would be of value in expediting the prosecution of this application, he is cordially invited to telephone the undersigned counsel to arrange for such a conference.

Date: Dec. 7, 2005

Respectfully submitted,

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